



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Features

- Low Gate Charge
- Low $R_{DS(ON)}$:
 - $24m\Omega @ V_{GS} = 4.5V$
 - $28m\Omega @ V_{GS} = 2.5V$
 - $34m\Omega @ V_{GS} = 1.8V$
- Low Input/Output Leakage
- **ESD Protected up to 2kV HBM**
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

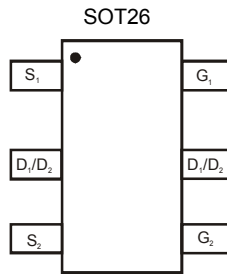
- Case: SOT26
- Case Material - Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin annealed over Copper leadframe Solderable per MIL-STD-202, Method 208 **(e3)**
- Terminal Connections: See Diagram
- Weight: 0.0008 grams (approximate)



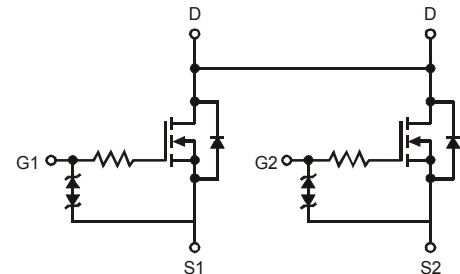
ESD PROTECTED TO 2kV



Top View



Top View
Pin Configuration



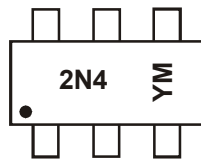
N-Channel
Equivalent Circuit
N-Channel

Ordering Information (Note 4)

Part Number	Case	Packaging
DMG6968UDM-7	SOT26	3000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



2N4 = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: W = 2009)
 M = Month (ex: 9 = September)

Date Code Key

Year	2008	2009	2010	2011	2012	2013	2014	2015
Code	V	W	X	Y	Z	A	B	C

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	20	V
Gate-Source Voltage (Note 5)	V_{GSS}	± 12	V
Drain Current (Note 6) Continuous	I_D	$T_A = +25^\circ\text{C}$	6.5
		$T_A = +70^\circ\text{C}$	5.2
Pulsed Drain Current (Note 7)	I_{DM}	30	A

Thermal Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

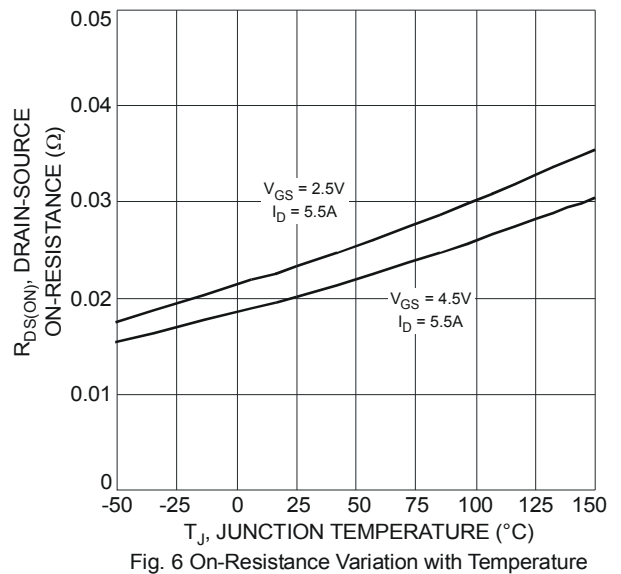
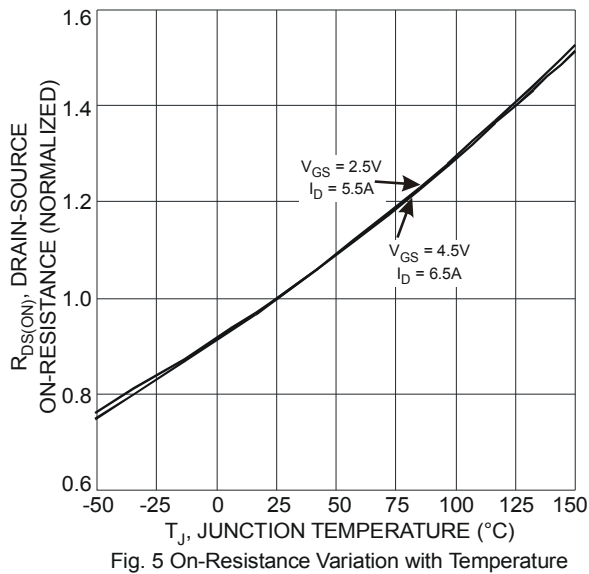
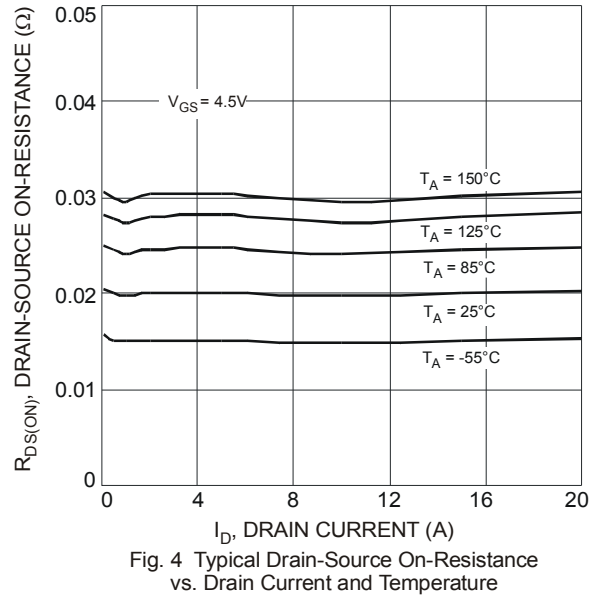
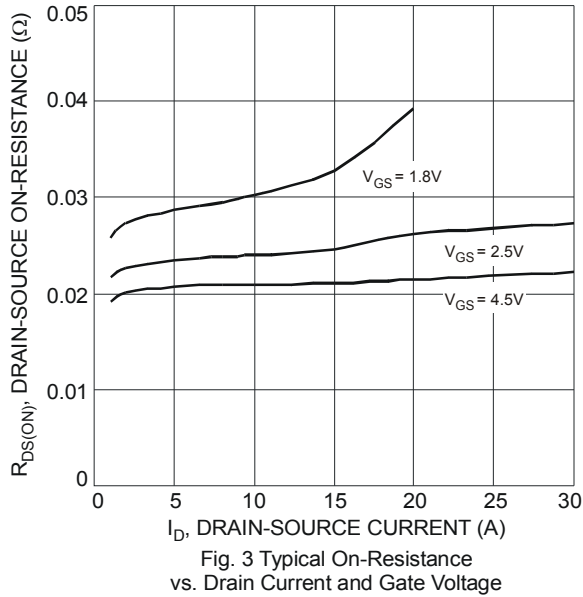
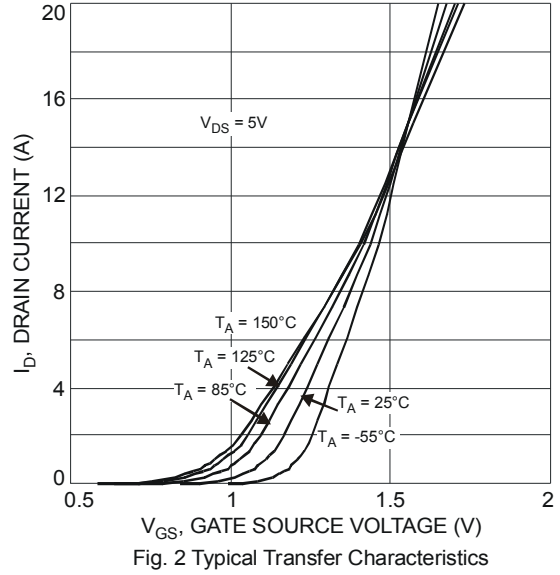
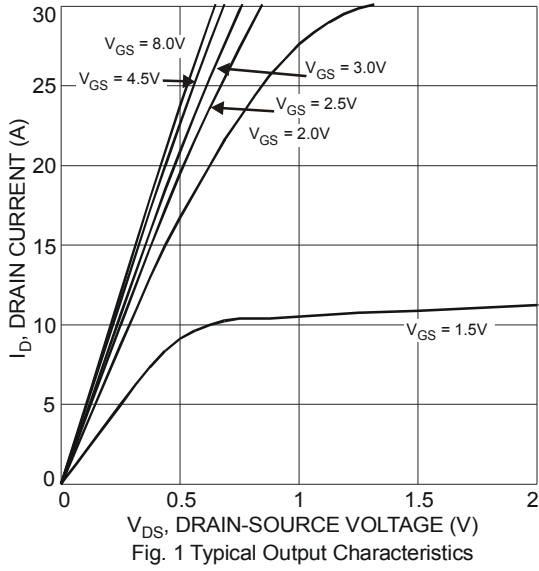
Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 6)	P_D	0.85	W
Thermal Resistance, Junction to Ambient (Note 6) $t \leq 10\text{s}$	$R_{\theta JA}$	147	$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

- Notes:
- AEC-Q101 VGS maximum is $\pm 9.6\text{V}$.
 - Device mounted on 1"x1", FR-4 PC board with 2 oz. Copper and test pulse width $t \leq 10\text{s}$.
 - Repetitive Rating, pulse width limited by junction temperature.

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
STATIC CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	20	—	—	V	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$
Zero Gate Voltage Drain Current	I_{DSS}	—	—	1	μA	$V_{DS} = 20\text{V}, V_{GS} = 0\text{V}$
Gate-Body Leakage Current	I_{GSS}	—	—	± 10	μA	$V_{DS} = 0\text{V}, V_{GS} = \pm 10\text{V}$
Gate-Source Breakdown Voltage	BV_{SGS}	± 12	—	—	V	$V_{DS} = 0\text{V}, I_G = \pm 250\mu\text{A}$
Gate Threshold Voltage	$V_{GS(th)}$	0.5	—	0.9	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
Static Drain-Source On-Resistance (Note 8)	$R_{DS(on)}$	—	17	24	$\text{m}\Omega$	$V_{GS} = 4.5\text{V}, I_D = 6.5\text{A}$
			20	28		$V_{GS} = 2.5\text{V}, I_D = 5.5\text{A}$
			26	34		$V_{GS} = 1.8\text{V}, I_D = 3.5\text{A}$
Forward Transfer Admittance	$ Y_{FS} $	—	8	—	S	$V_{DS} = 10\text{V}, I_D = 5\text{A}$
Diode Forward Voltage (Note 8)	V_{SD}	—	0.7	1.0	V	$I_S = 2.25\text{A}, V_{GS} = 0\text{V}$
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	C_{iss}	—	143	—	pF	$V_{DS} = 10\text{V}, V_{GS} = 0\text{V}$ $f = 1.0\text{MHz}$
Output Capacitance	C_{oss}	—	74	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	29	—	pF	
Gate Resisistance	R_G	—	202	—	Ω	$V_{GS} = 0\text{V}, V_{DS} = 0\text{V}, f = 1\text{MHz}$
SWITCHING CHARACTERISTICS (Note 9)						
Total Gate Charge	Q_g	—	8.8	—	nC	$V_{GS} = 4.5\text{V}, V_{DS} = 10\text{V}, I_D = 6.5\text{A}$
Gate-Source Charge	Q_{gs}	—	1.4	—	nC	
Gate-Drain Charge	Q_{gd}	—	3.0	—	nC	
Turn-On Delay Time	$t_{D(on)}$	—	53	—	ns	$V_{DD} = 10\text{V}, V_{GS} = 4.5\text{V},$ $R_L = 10\Omega, R_G = 6\Omega$
Turn-On Rise Time	t_r	—	78	—	ns	
Turn-Off Delay Time	$t_{D(off)}$	—	562	—	ns	
Turn-Off Fall Time	t_f	—	234	—	ns	

- Notes:
- Test pulse width $t = 300\text{ms}$.
 - Guaranteed by design. Not subject to production testing.



NEW PRODUCT

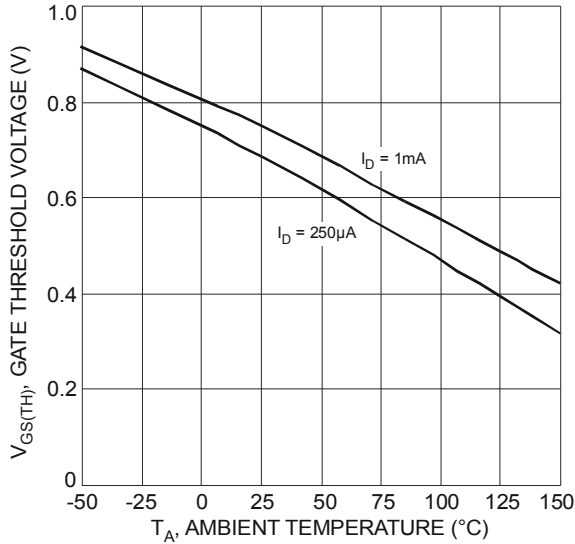


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

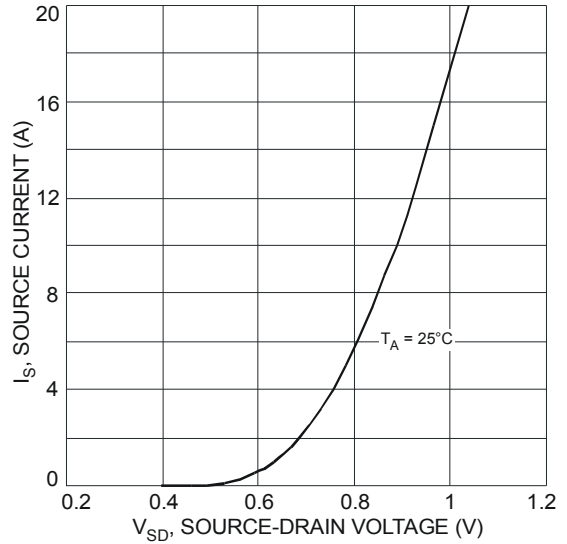


Fig. 8 Diode Forward Voltage vs. Current

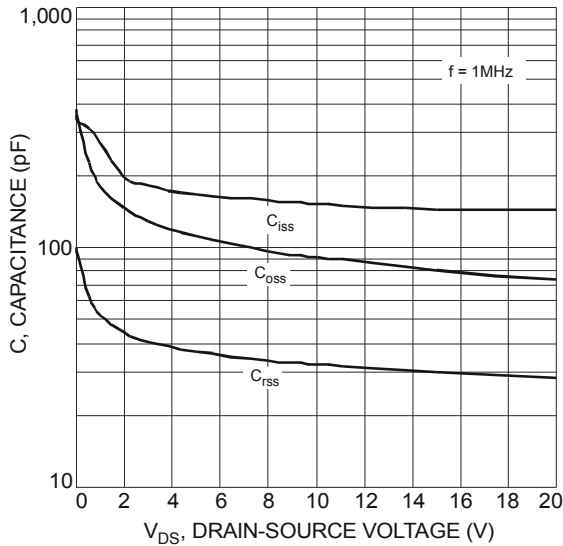


Fig. 9 Typical Capacitance

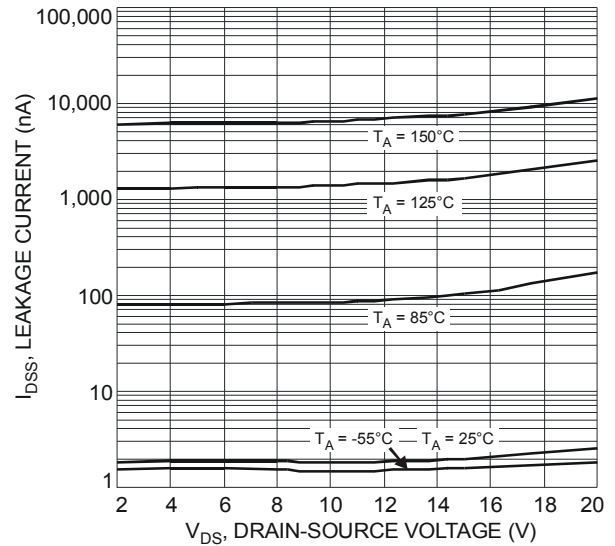


Fig. 10 Typical Drain-Source Leakage Current vs. Drain-Source Voltage

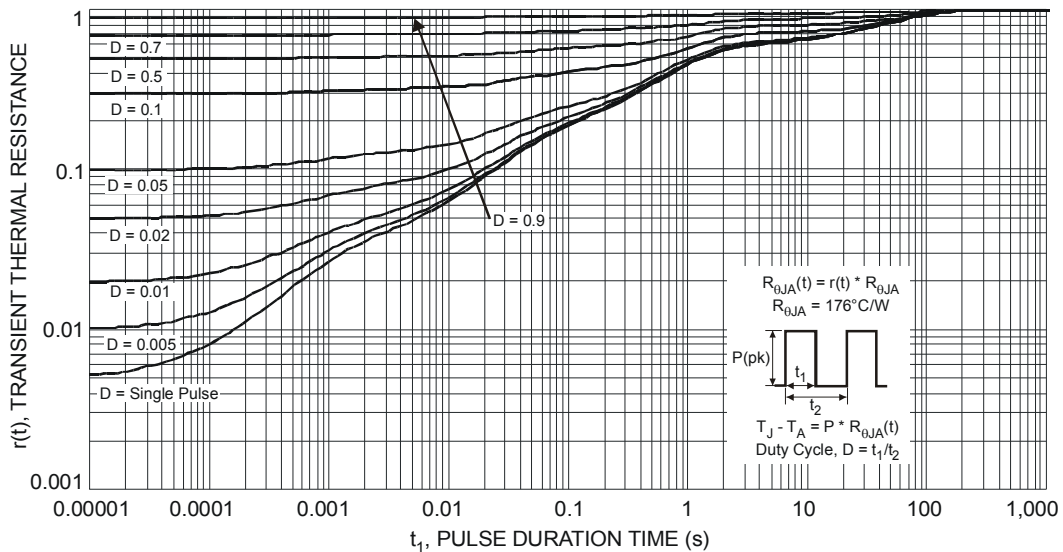
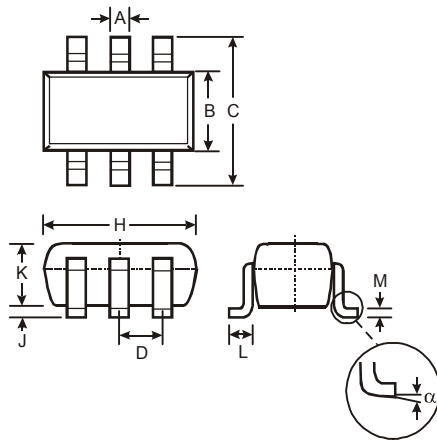


Fig. 11 Transient Thermal Response

Package Outline Dimensions

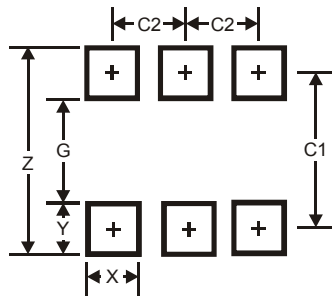
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



SOT26			
Dim	Min	Max	Typ
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	—	—	0.95
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
α	0°	8°	—
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
Z	3.20
G	1.60
X	0.55
Y	0.80
C1	2.40
C2	0.95

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